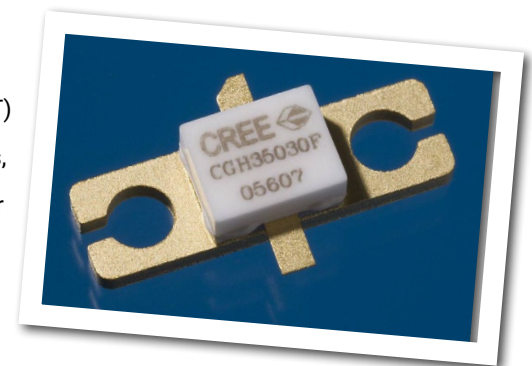


# CGH35030F

30 W, 3300-3900 MHz, 28V, GaN HEMT for WiMAX

Cree's CGH35030F is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGH35030F ideal for 3.3-3.9GHz WiMAX and BWA amplifier applications. The transistor is supplied in a ceramic/metal flange package.



Package Type: 440166  
PN: CGH35030F

## Typical Performance Over 3.3-3.8GHz ( $T_c = 25^\circ\text{C}$ ) of Demonstration Amplifier

Parameter	3.3 GHz	3.4 GHz	3.5 GHz	3.6 GHz	3.7 GHz	3.8 GHz	Units
Small Signal Gain	11.6	11.8	11.8	12.0	12.4	13.0	dB
EVM at $P_{AVE} = 23$ dBm	2.42	2.26	2.09	2.11	2.13	2.38	%
EVM at $P_{AVE} = 36$ dBm	1.97	1.74	1.68	1.79	2.01	2.37	%
Drain Efficiency @ 36 dBm	20.8	21.9	23.5	25.4	27.4	29.1	%
Input Return Loss	12.3	8.5	6.1	5.4	6.1	9.0	dB

**Note:**

Measured in the CGH35030F-AMP amplifier circuit, under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5 ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

## Features



- 3.3 - 3.9 GHz Operation
- 30 W Peak Power Capability
- 12 dB Small Signal Gain
- 4.0 W  $P_{AVE}$  at < 2.0 % EVM
- 25 % Drain Efficiency at 4 W  $P_{AVE}$
- WiMAX Fixed Access 802.16-2004 OFDM
- WiMAX Mobile Access 802.16e OFDMA

Large Signal Models Available for ADS and MWO



## Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

Parameter	Symbol	Rating	Units	Units
Drain-Source Voltage	$V_{DS}$	84	Volts	25°C
Gate-to-Source Voltage	$V_{GS}$	-10, +2	Volts	25°C
Power Dissipation	$P_{DISS}$	14	Watts	
Storage Temperature	$T_{STG}$	-65, +150	°C	
Operating Junction Temperature	$T_J$	225	°C	
Maximum Forward Gate Current	$I_{GMAX}$	4.0	mA	25°C
Maximum Drain Current <sup>1</sup>	$I_{DMAX}$	3.0	A	25°C
Soldering Temperature <sup>2</sup>	$T_S$	245	°C	
Screw Torque	$\tau$	60	in-oz	
Thermal Resistance, Junction to Case <sup>3</sup>	$R_{\theta JC}$	4.8	°C/W	85°C
Case Operating Temperature <sup>3</sup>	$T_C$	-40, +150	°C	

### Notes:

<sup>1</sup> Current limit for long term, reliable operation.

<sup>2</sup> Refer to the Application Note on soldering at [www.cree.com/RF/Documnet-Library](http://www.cree.com/RF/Documnet-Library)

<sup>3</sup> Measured for the CGH35030F at  $P_{DISS} = 14$  W

## Electrical Characteristics ( $T_C = 25^\circ\text{C}$ )

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>DC Characteristics<sup>1</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.0	-2.3	$V_{DC}$	$V_{DS} = 10$ V, $I_D = 7.2$ mA
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-2.7	-	$V_{DC}$	$V_{DS} = 28$ V, $I_D = 120$ mA
Saturated Drain Current	$I_{DS}$	5.8	7.0	-	A	$V_{DS} = 6.0$ V, $V_{GS} = 2$ V
Drain-Source Breakdown Voltage	$V_{BR}$	120	-	-	$V_{DC}$	$V_{GS} = -8$ V, $I_D = 7.2$ mA
<b>RF Characteristics<sup>2,3</sup> (<math>T_C = 25^\circ\text{C}</math>, <math>F_0 = 3.5</math> GHz unless otherwise noted)</b>						
Small Signal Gain	$G_{SS}$	10	11.5	-	dB	$V_{DD} = 28$ V, $I_{DQ} = 120$ mA, $P_{AVE} = 23$ dBm
Drain Efficiency <sup>4</sup>	$\eta$	20	25	-	%	$V_{DD} = 28$ V, $I_{DQ} = 120$ mA, $P_{AVE} = 36$ dBm
Back-Off Error Vector Magnitude	$EVM_1$	-	2.5	-	%	$V_{DD} = 28$ V, $I_{DQ} = 120$ mA, $P_{AVE} = 23$ dBm
Error Vector Magnitude	$EVM_2$	-	2.0	-	%	$V_{DD} = 28$ V, $I_{DQ} = 120$ mA, $P_{AVE} = 36$ dBm
Output Mismatch Stress	VSWR	-	-	10 : 1	$\Psi$	No damage at all phase angles, $V_{DD} = 28$ V, $I_{DQ} = 120$ mA
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{GS}$	-	9.0	-	pF	$V_{DS} = 28$ V, $V_{gs} = -8$ V, $f = 1$ MHz
Output Capacitance	$C_{DS}$	-	2.6	-	pF	$V_{DS} = 28$ V, $V_{gs} = -8$ V, $f = 1$ MHz
Feedback Capacitance	$C_{GD}$	-	0.4	-	pF	$V_{DS} = 28$ V, $V_{gs} = -8$ V, $f = 1$ MHz

### Notes:

<sup>1</sup> Measured on wafer prior to packaging.

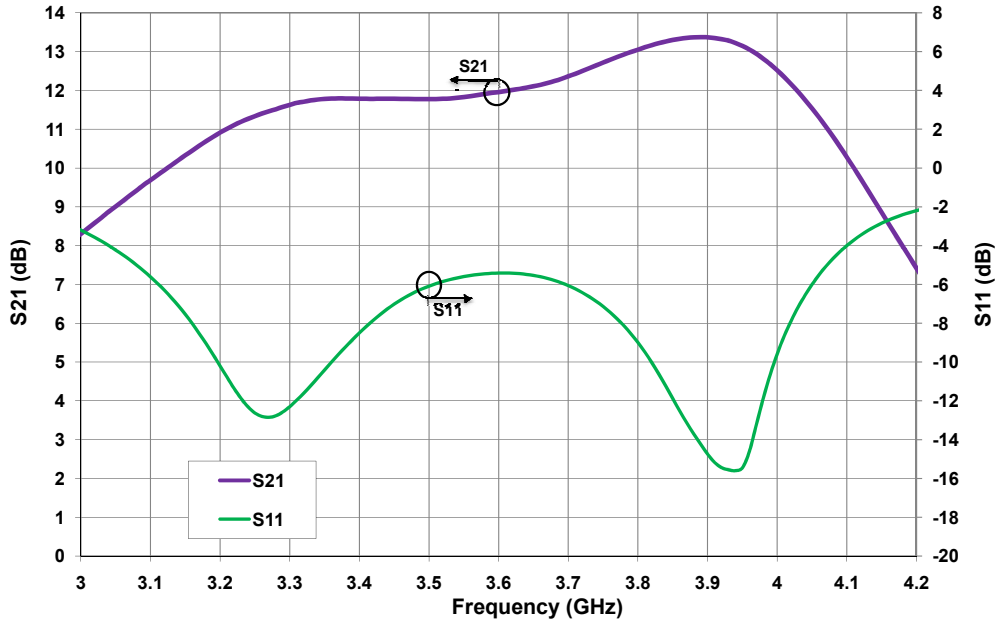
<sup>2</sup> Measured in the CGH35030F-AMP test fixture.

<sup>3</sup> Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5 ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

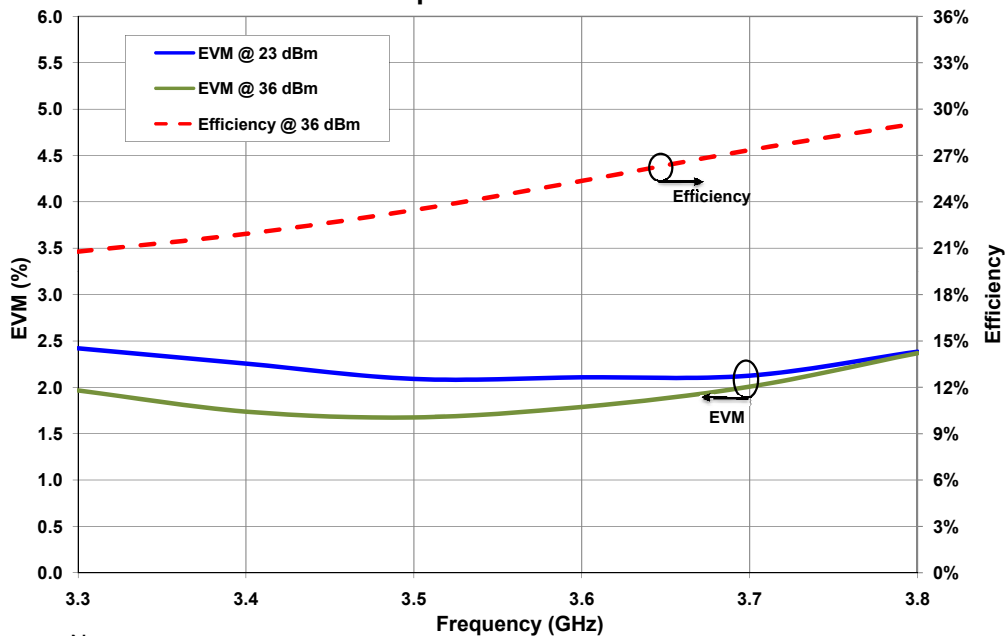
<sup>4</sup> Drain Efficiency =  $P_{OUT} / P_{DC}$

## Typical WiMAX Performance

**Figure 1.- Gain and Return Loss vs Frequency measured in Broadband Amplifier Circuit CGH35030F-AMP1**  
 $V_{DD} = 28\text{ V}, I_{DQ} = 120\text{ mA}$



**Figure 2.- Typical EVM and Efficiency at 23 dBm and 36 dBm vs Frequency measured in Broadband Amplifier Circuit CGH35030F-AMP**

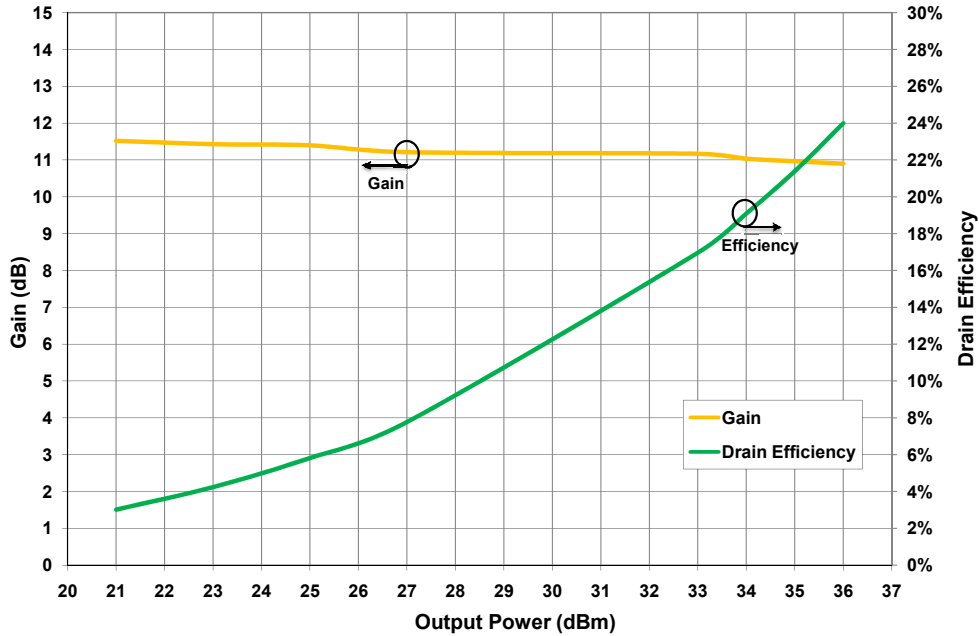


**Note:**

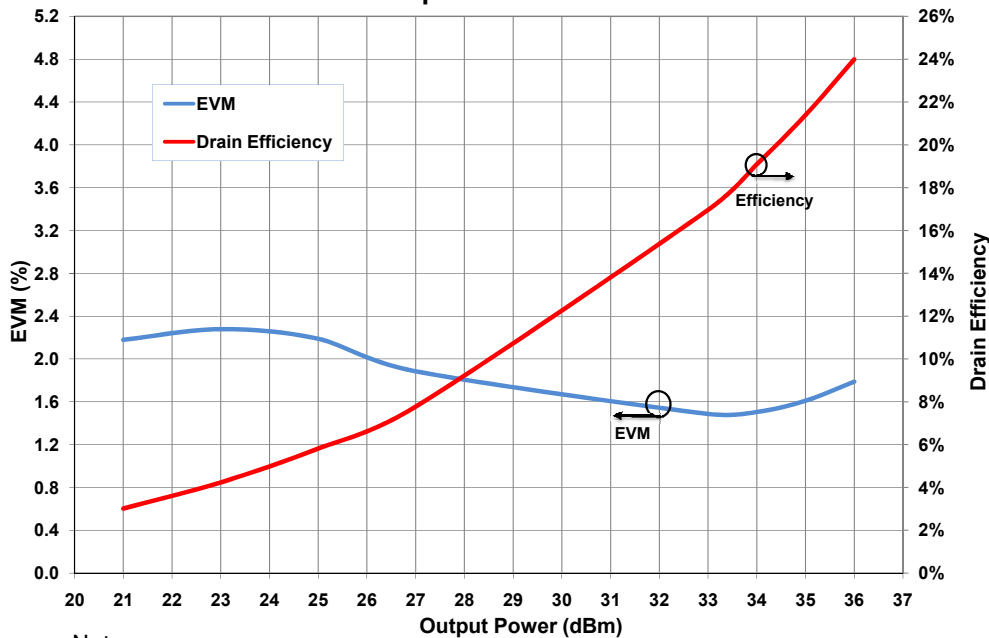
Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

## Typical WiMAX Performance

**Figure 3.- Gain and Return Loss vs Frequency measured in Broadband Amplifier Circuit CGH35030F-AMP**  
 $V_{DD} = 28\text{ V}, I_{DQ} = 120\text{ mA}$



**Figure 4.- Typical EVM and Efficiency vs Frequency measured in Broadband Amplifier Circuit CGH35030F-AMP**

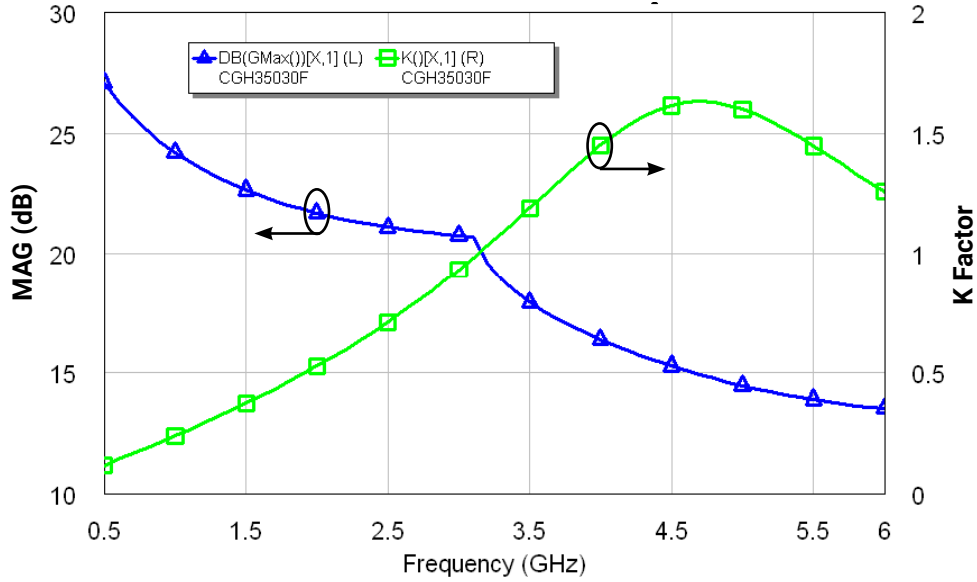


Note:

Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

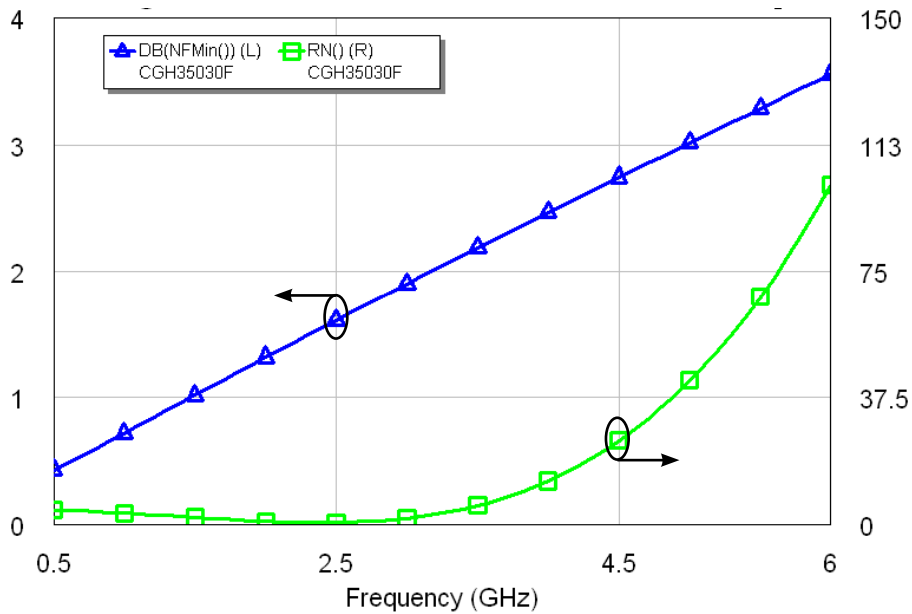
## Typical Performance

**Figure 5.- Simulated Maximum Available Gain and K Factor of the CGH35030F**  
 $V_{DD} = 28\text{ V}, I_{DQ} = 120\text{ mA}$

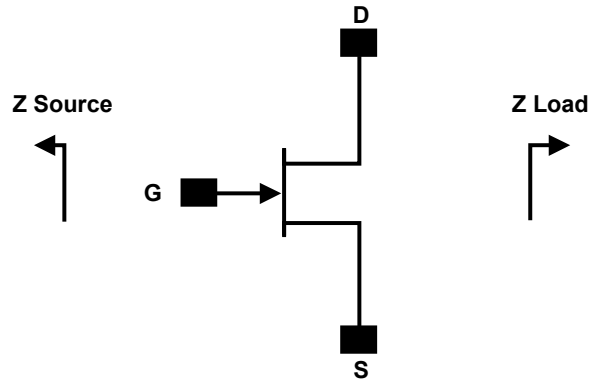


## Typical Noise Performance

**Figure 6.- Simulated Minimum Noise Figure and Noise Resistance vs Frequency of the CGH35030**  
 $V_{DD} = 28\text{ V}, I_{DQ} = 120\text{ mA}$



## Source and Load Impedances



Frequency (MHz)	Z Source	Z Load
3300	3.3 - j9.2	13.4 - j11.4
3400	3.9 - j8.6	12.2 - j10.4
3500	4.5 - j8.5	11.1 - j9.4
3600	4.7 - j8.8	10.2 - j8.2
3700	4.3 - j9.0	9.5 - j7.1

Note 1.  $V_{DD} = 28V$ ,  $I_{DQ} = 120\text{ mA}$  in the 440166 package.

Note 2. Impedances are extracted from the CGH35030-AMP demonstration amplifier and are not source and load pull data derived from the transistor.

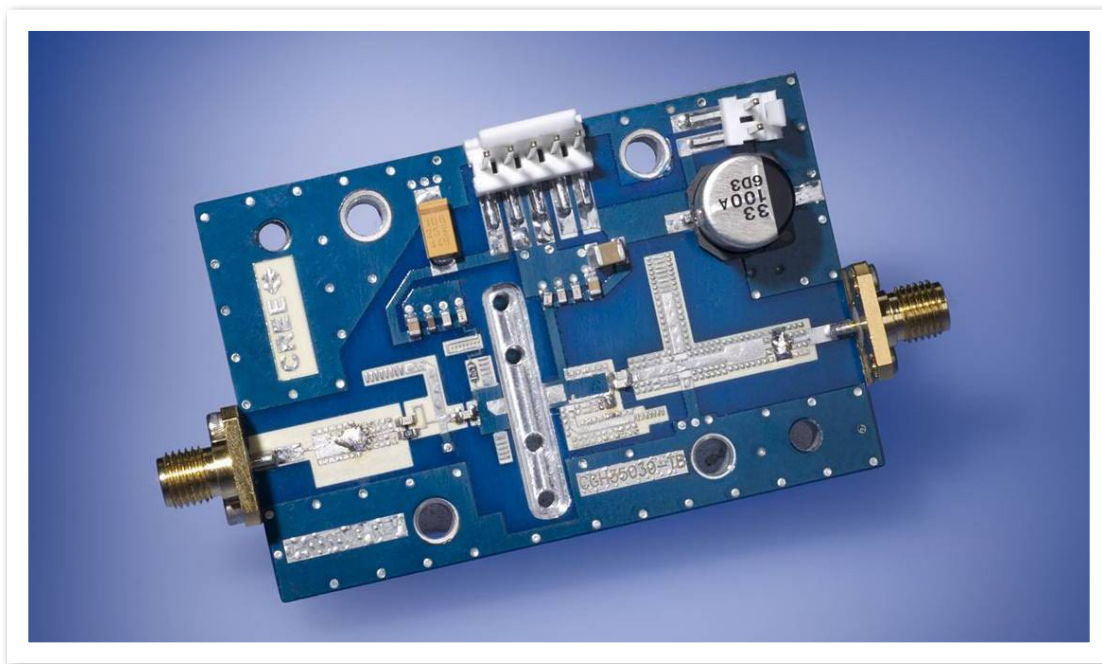
## Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Test Methodology
Human Body Model	HBM	1A (> 250 V)	JEDEC JESD22 A114-D
Charge Device Model	CDM	II (200 < 500 V)	JEDEC JESD22 C101-C

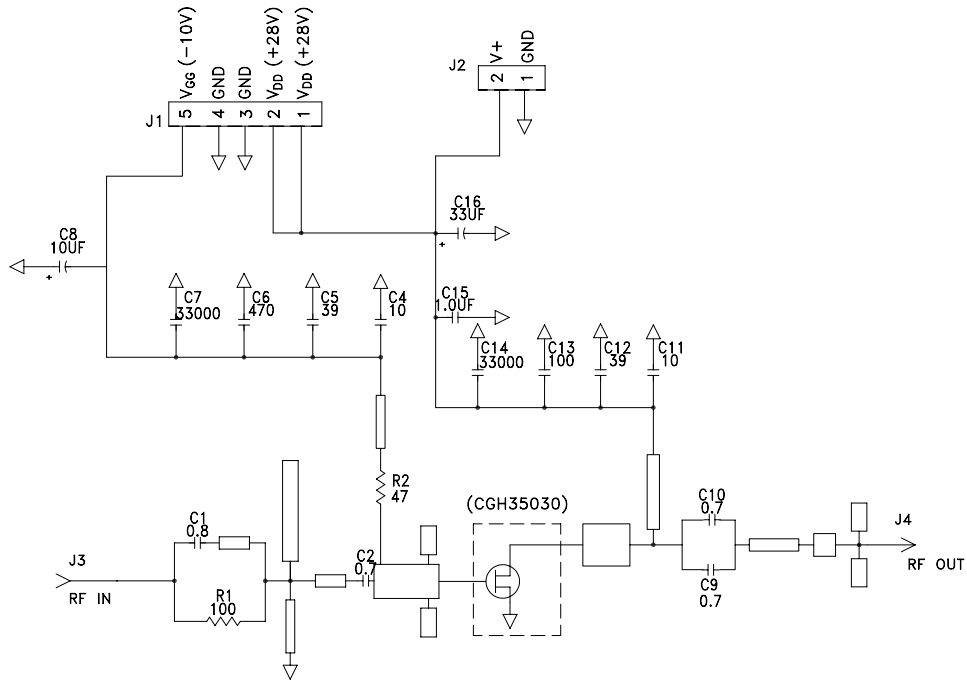
## CGH35030F-AMP Demonstration Amplifier Circuit Bill of Materials

Designator	Description	Qty
R1	RES,1/16W,0603,1%,100 OHMS	1
R2	RES,1/16W,0603,1%,47 OHMS	1
C6	CAP,470PF,10%,100V, 0603	1
C17	CAP,33 UF,20%, G CASE	1
C16	CAP,1.0UF,100V,10%,X7R,1210	1
C8	CAP 10UF 16V TANTALUM	1
C13	CAP,100.0pF,+/-5%,0603	1
C1	CAP,0.8pF,+/-0.05pF,0603,ATC	1
C2,C9,C10	CAP,0.7pF,+/-0.05pF,0603,ATC	3
C4,C11	CAP,10.0pF,+/-5%,0603,ATC	2
C5,C12	CAP,39pF,+/-5%,0603,ATC	2
C7,C14	CAP,33000PF,0805,100V,X7R	2
J3,J4	CONN SMA STR PANEL JACK RECP	1
J2	HEADER RT>PLZ.1CEN LK 2 POS	1
J1	HEADER RT>PLZ .1CEN LK 5POS	1
-	PCB,RO4350B,Er = 3.48,h = 20 mil	1
-	CGH35030F	1

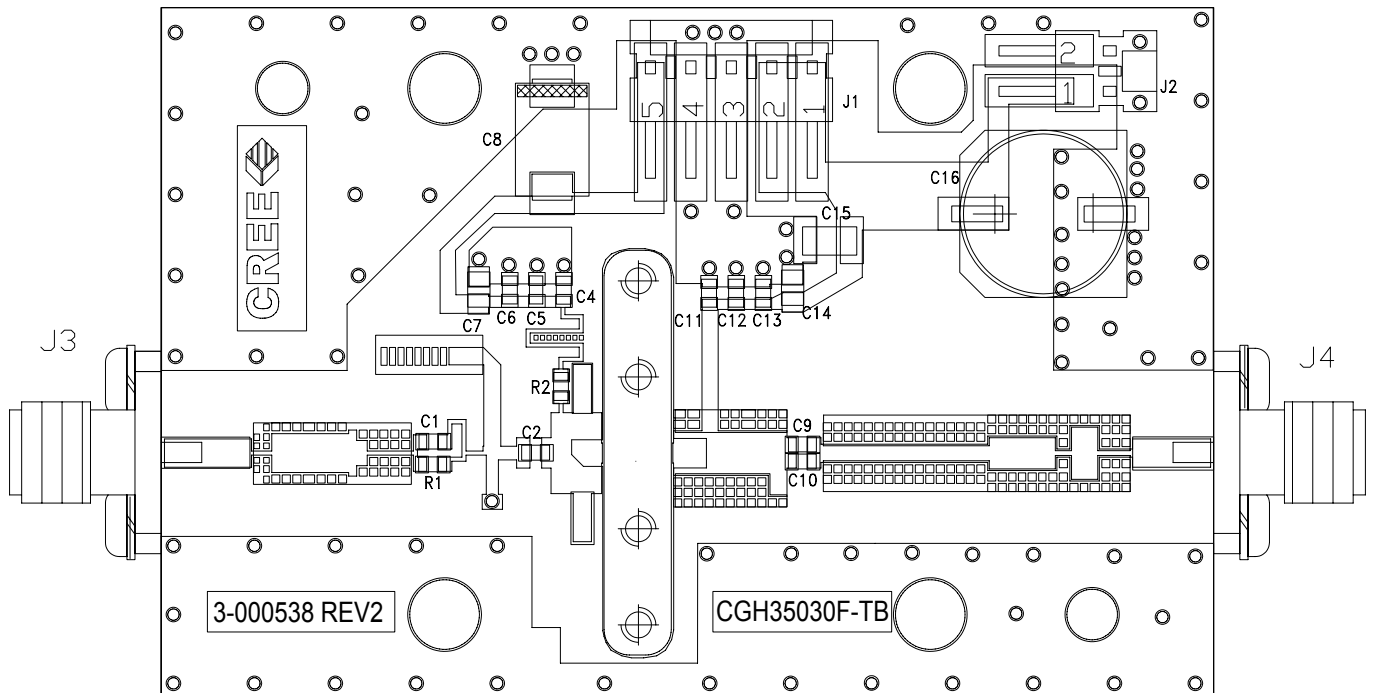
## CGH35030F-AMP Demonstration Amplifier Circuit



## CGH35030F-AMP Demonstration Amplifier Circuit Schematic



## CGH35030F-AMP Demonstration Amplifier Circuit Outline



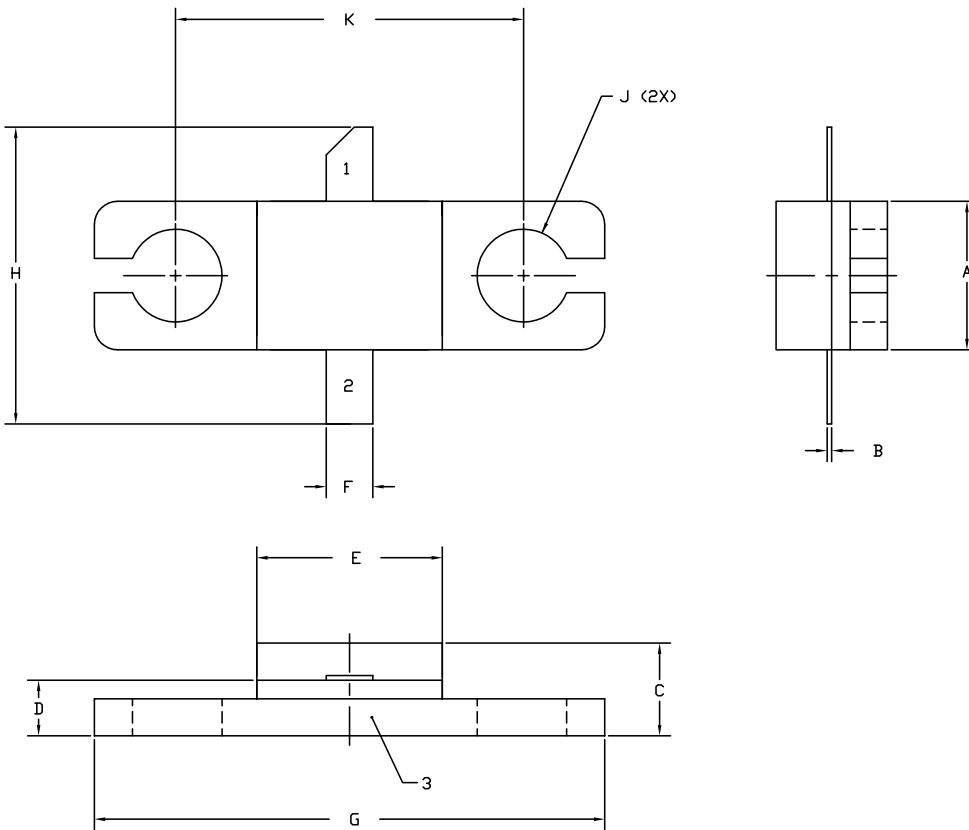


**Typical Package S-Parameters for CGH35030**  
 (Small Signal,  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 120\text{ mA}$ , angle in degrees)

Frequency	Mag S11	Ang S11	Mag S21	Ang S21	Mag S12	Ang S12	Mag S22	Ang S22
500 MHz	0.909	-152.96	11.93	92.31	0.023	6.73	0.393	-144.30
600 MHz	0.907	-158.23	10.00	87.72	0.023	3.05	0.401	-147.24
700 MHz	0.907	-162.20	8.59	83.77	0.023	0.01	0.410	-149.13
800 MHz	0.907	-165.34	7.51	80.24	0.023	-2.59	0.420	-150.43
900 MHz	0.907	-167.92	6.66	76.99	0.023	-4.90	0.431	-151.37
1.0 GHz	0.908	-170.10	5.98	73.96	0.023	-6.97	0.442	-152.11
1.1 GHz	0.908	-172.00	5.41	71.09	0.022	-8.87	0.454	-152.74
1.2 GHz	0.909	-173.67	4.94	68.35	0.022	-10.62	0.466	-153.31
1.3 GHz	0.910	-175.19	4.53	65.71	0.022	-12.23	0.478	-153.87
1.4 GHz	0.911	-176.58	4.18	63.16	0.022	-13.73	0.490	-154.44
1.5 GHz	0.912	-177.86	3.88	60.70	0.021	-15.13	0.503	-155.02
1.6 GHz	0.913	-179.07	3.61	58.30	0.021	-16.42	0.515	-155.64
1.7 GHz	0.914	-179.79	3.38	55.96	0.020	-17.62	0.528	-156.28
1.8 GHz	0.915	-178.71	3.17	53.68	0.020	-18.72	0.540	-156.96
1.9 GHz	0.916	-177.66	2.98	51.45	0.020	-19.73	0.552	-157.67
2.0 GHz	0.917	-176.65	2.81	49.27	0.019	-20.64	0.564	-158.41
2.1 GHz	0.918	-175.67	2.66	47.14	0.019	-21.45	0.576	-159.17
2.2 GHz	0.919	-174.72	2.52	45.05	0.018	-22.17	0.587	-159.97
2.3 GHz	0.921	-173.78	2.39	43.00	0.018	-22.78	0.598	-160.79
2.4 GHz	0.922	-172.86	2.27	40.99	0.017	-23.28	0.609	-161.62
2.5 GHz	0.923	-171.95	2.16	39.02	0.017	-23.68	0.619	-162.48
2.6 GHz	0.924	-171.05	2.06	37.08	0.016	-23.96	0.629	-163.36
2.7 GHz	0.925	-170.16	1.97	35.18	0.016	-24.11	0.639	-164.24
2.8 GHz	0.926	-169.28	1.89	33.31	0.015	-24.14	0.648	-165.15
2.9 GHz	0.927	-168.41	1.81	31.47	0.015	-24.04	0.657	-166.06
3.0 GHz	0.927	-167.53	1.74	29.66	0.015	-23.79	0.666	-166.98
3.2 GHz	0.929	-165.79	1.61	26.12	0.014	-22.85	0.682	-168.84
3.4 GHz	0.931	-164.05	1.49	22.69	0.013	-21.25	0.697	-170.73
3.6 GHz	0.932	-162.30	1.39	19.35	0.012	-18.94	0.711	-172.64
3.8 GHz	0.933	-160.54	1.30	16.10	0.012	-15.90	0.724	-174.56
4.0 GHz	0.934	-158.76	1.23	12.92	0.011	-12.15	0.735	-176.49
4.2 GHz	0.935	-156.96	1.16	9.80	0.011	-7.76	0.746	-178.43
4.4 GHz	0.936	-155.14	1.10	6.75	0.011	-2.91	0.755	-179.63
4.6 GHz	0.937	-153.27	1.04	3.74	0.011	2.16	0.764	-177.67
4.8 GHz	0.937	-151.38	0.99	0.78	0.011	7.15	0.772	-175.70
5.0 GHz	0.938	-149.44	0.95	-2.15	0.012	11.82	0.779	-173.71
5.2 GHz	0.938	-147.46	0.91	-5.05	0.013	15.96	0.786	-171.71
5.4 GHz	0.938	-145.42	0.88	-7.92	0.014	19.45	0.791	-169.69
5.6 GHz	0.938	-143.34	0.85	-10.79	0.015	22.27	0.796	-167.65
5.8 GHz	0.938	-141.19	0.82	-13.65	0.016	24.42	0.801	-165.58
6.0 GHz	0.937	-138.98	0.79	-16.50	0.017	25.96	0.805	-163.48

To download the s-parameters in s2p format, go to the [CGH35030F Product Page](#) and click on the documentation tab.

## Product Dimensions CGH35030F (Package Type – 440166)



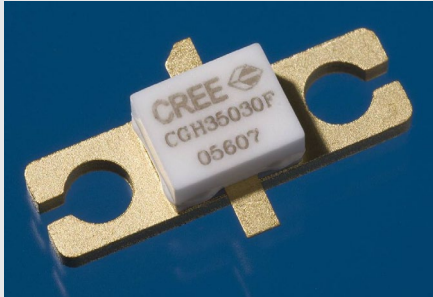
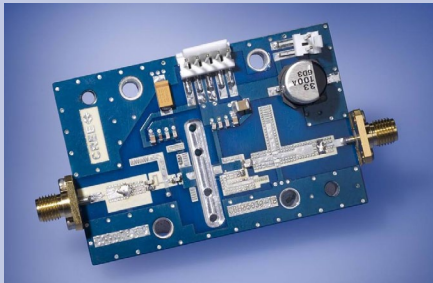
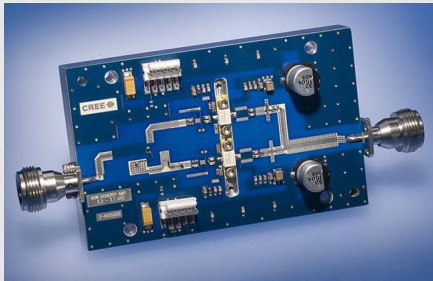
### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE Ni/AU

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.155	0.165	3.94	4.19
B	0.004	0.006	0.10	0.15
C	0.115	0.135	2.92	3.43
D	0.057	0.067	1.45	1.70
E	0.195	0.205	4.95	5.21
F	0.045	0.055	1.14	1.40
G	0.545	0.555	13.84	14.09
H	0.280	0.360	7.11	9.14
J	∅ .100		2.54	
K	0.375		9.53	

PIN 1. GATE  
 PIN 2. DRAIN  
 PIN 3. SOURCE

## Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGH35030F	GaN HEMT	Each	
CGH35030-TB	Test board without GaN HEMT	Each	
CGH35030F-AMP	Test board with GaN HEMT installed	Each	



## Disclaimer

Specifications are subject to change without notice. Cree, Inc. believes the information contained within this data sheet to be accurate and reliable. However, no responsibility is assumed by Cree for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Cree. Cree makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose. "Typical" parameters are the average values expected by Cree in large quantities and are provided for information purposes only. These values can and do vary in different applications and actual performance can vary over time. All operating parameters should be validated by customer's technical experts for each application. Cree products are not designed, intended or authorized for use as components in applications intended for surgical implant into the body or to support or sustain life, in applications in which the failure of the Cree product could result in personal injury or death or in applications for planning, construction, maintenance or direct operation of a nuclear facility.

For more information, please contact:

Cree, Inc.  
4600 Silicon Drive  
Durham, North Carolina, USA 27703  
[www.cree.com/RF](http://www.cree.com/RF)

Sarah Miller  
Marketing  
Cree, RF Components  
1.919.407.5302

Ryan Baker  
Marketing & Sales  
Cree, RF Components  
1.919.407.7816

Tom Dekker  
Sales Director  
Cree, RF Components  
1.919.407.5639